

STW9NK95Z

N-channel 950 V - 1.15 Ω - 7 A - TO-247 Zener-protected SuperMESHTM Power MOSFET

Features

Туре	V _{DSS}	oss R _{DS(on)} Max		Pw	
STW9NK95Z	950 V	< 1.38 Ω	7 A	160 W	

- Extremely high dv/dt capability
- 100% avalanche tested
- Gate charge minimized

Application

■ Switching applications

Description

The SuperMESH™ series is obtained through an extreme optimization of ST's well established strip-based PowerMESH™ layout. In addition to pushing on-resistance significantly down, special care is taken to ensure a very good dv/dt capability for the most demanding applications.

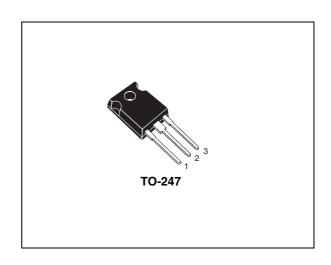


Figure 1. Internal schematic diagram

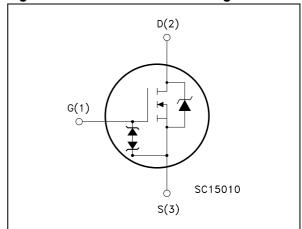


Table 1. Device summary

Order code	Marking	Package	Packaging
STW9NK95Z	9NK95Z	TO-247	Tube

Contents STW9NK95Z

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STW9NK95Z Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V _{GS} = 0)	950	V
V _{GS}	Gate-source voltage	± 30	V
I _D	Drain current (continuous) at T _C = 25 °C	7	Α
I _D	Drain current (continuous) at T _C =100 °C	4.41	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	28	Α
P _{TOT}	Total dissipation at T _C = 25 °C	160	W
	Derating Factor	1.28	W/°C
Vesd(G-S)	G-S ESD (HBM C=100 pF, R=1.5 kΩ)	4000	V
dv/dt ⁽²⁾	Peak diode recovery voltage slope	4.5	V/ns
T _J T _{stg}	Operating junction temperature Storage temperature	-55 to 150	°C

^{1.} Pulse width limited by safe operating area

Table 3. Thermal data

Symbol Parameter		Value	Unit
R _{thj-case}	Thermal resistance junction-case max	0.78	°C/W
R _{thj-a}	Thermal resistance junction-ambient max	50	°C/W
T _I	Maximum lead temperature for soldering purpose	300	°C

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_J Max)	7	Α
E _{AS}	Single pulse avalanche energy (starting T _J =25 °C, I _D =I _{AS} , V _{DD} =50 V) (see Figure 17)and (see Figure 18)	300	mJ

^{2.} $I_{SD} \leq$ 7 A, di/dt \leq 100 A/ μ s, $V_{DD} \leq$ 80% $V_{(BR)DSS}$

Electrical characteristics STW9NK95Z

2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Table 5. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	950			٧
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V_{DS} = max rating, V_{DS} = max rating @125 °C			1 50	μA μA
I _{GSS}	Gate body leakage current (V _{DS} = 0)	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$			±10	μΑ
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 100 \mu A$	3	3.75	4.5	٧
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10 V, I _D = 3.6 A		1.15	1.38	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
g _{fs} ⁽¹⁾	Forward transconductance	$V_{DS} = 15 \text{ V}, I_D = 3.6 \text{ A}$		5.7		S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 \text{ V, f=1 MHz,}$ $V_{GS} = 0$		2256 189 30		pF pF pF
C _{oss eq} ⁽²⁾	Equivalent output capacitance	V _{GS} =0, V _{DS} =0 to 760 V		37		pF
R_{G}	Intrinsic gate resistance	f=1 MHz, open drain		1.6		Ω
$egin{array}{c} Q_{g} \ Q_{gs} \ Q_{gd} \end{array}$	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 760 V, I_{D} = 7.2 A V_{GS} = 10 V (see Figure 15)		56 10 30		nC nC nC

^{1.} Pulsed: pulse duration=300µs, duty cycle 1.5%

^{2.} $C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time Rise Time	V_{DD} = 475 V, I_{D} = 3.6 A, R_{G} = 4.7 Ω , V_{GS} = 10 V (see Figure 14) (see Figure 19)		22 15		ns ns
t _{d(off)}	Turn-off delay time Fall time	V_{DD} = 475 V, I_{D} = 3.6 A, R_{G} = 4.7 Ω , V_{GS} = 10 V (see Figure 14) (see Figure 19)		51 22		ns ns

Table 8. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
BV _{GSO} ⁽¹⁾	Gate-source breakdown voltage	Igs=±1 mA(open drain)	30			٧

The built-in back-to-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.

Table 9. Source drain diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I _{SD}	Source-drain current				7	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)				28	Α
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 7.2 A, V _{GS} =0			1.6	٧
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 7.2 A, di/dt = 100 A/ μ s, V_{DD} = 60V, Tj = 25°C (see Figure 16)		660 5.9 18		ns μC Α
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 7.2 A, di/dt = 100 A/ μ s, V_{DD} = 60V, Tj = 150°C (see Figure 16)		800 7.4 18.6		ns μC A

^{1.} Pulse width limited by safe operating area

^{2.} Pulsed: pulse duration=300µs, duty cycle 1.5%

Electrical characteristics STW9NK95Z

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance

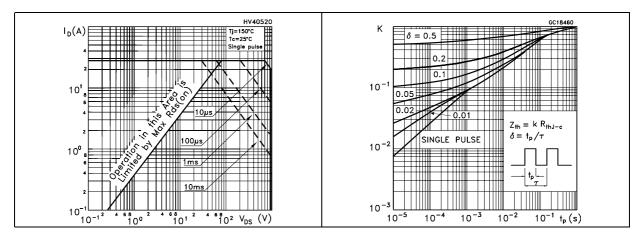


Figure 4. Output characteristics

Figure 5. Transfer characteristics

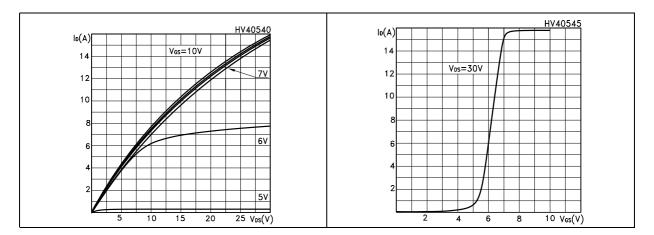
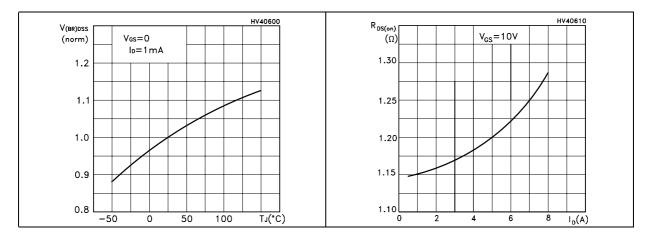


Figure 6. Normalized B_{VDSS} vs temperature

Figure 7. Static drain-source on resistance



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Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

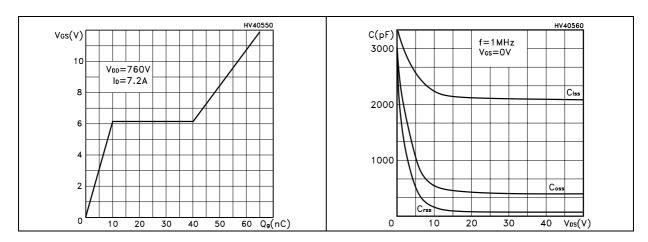


Figure 10. Normalized gate threshold voltage vs temperature

Figure 11. Normalized on resistance vs temperature

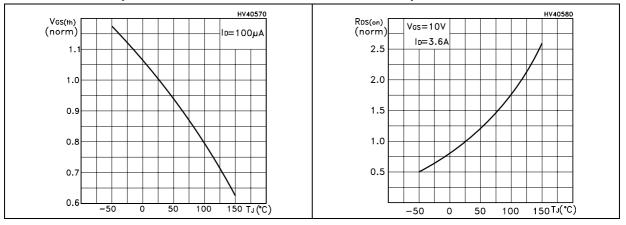
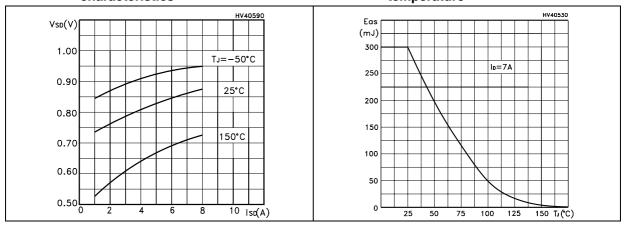


Figure 12. Source-drain diode forward characteristics

Figure 13. Maximum avalanche energy vs temperature



Test circuits STW9NK95Z

3 Test circuits

Figure 14. Switching times test circuit for resistive load

Figure 15. Gate charge test circuit

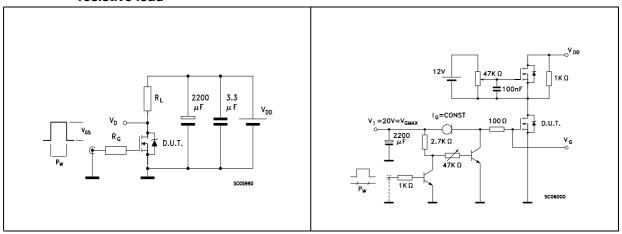


Figure 16. Test circuit for inductive load switching and diode recovery times

Figure 17. Unclamped Inductive load test circuit

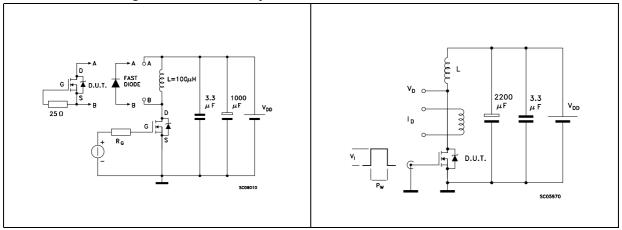
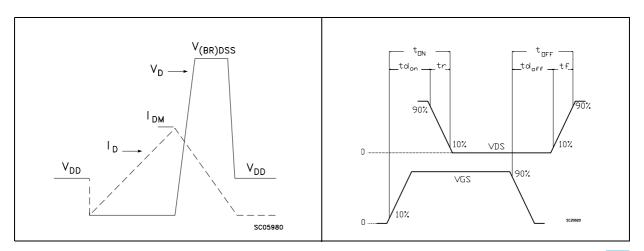


Figure 18. Unclamped inductive waveform

Figure 19. Switching time waveform

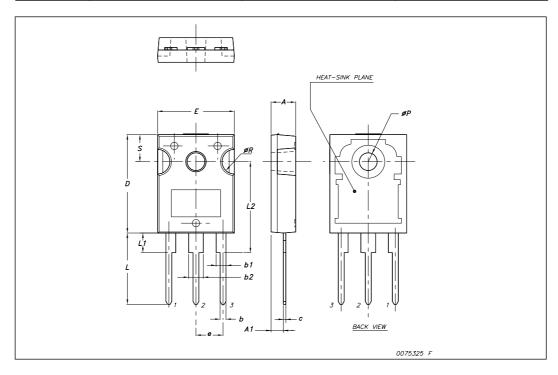


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-247 Mechanical data

Dim.	mm.			
Dilli.	Min.	Тур	Max.	
Α	4.85		5.15	
A1	2.20		2.60	
b	1.0		1.40	
b1	2.0		2.40	
b2	3.0		3.40	
С	0.40		0.80	
D	19.85		20.15	
E	15.45		15.75	
е		5.45		
L	14.20		14.80	
L1	3.70		4.30	
L2		18.50		
øΡ	3.55		3.65	
øR	4.50		5.50	
S		5.50		



STW9NK95Z Revision history

5 Revision history

Table 10. Document revision history

Date	Revision	Changes
11-Oct-2006	1	Initial release
03-Jul-2008	2	Updated Figure 6, Figure 7, Figure 9

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